

**RECORDATIC  
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PATENT (**

06-30-2008



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	Kai-Shun Mak
	Toy Drawing Board
Number	CHU/420DES/US
	June 20, 2008

Mail Stop Assignment Recordation Services Director of the United States Patent and Trademark Office, P.O. Box 1450, Alexandria, Virginia 22313-1450

Please record the attached document.

1. Name of conveying party(ies):

Kai-Shun Mak

2. Name and address of receiving party(ies):

Name: Hop Lee Cheong Industrial Company Limited  
Street Address: Block A1-A3, 7/F.  
Yip Fung Industrial Building  
28-36 Kwai Fung Crescent, Kwai Chung  
City, State, ZIP: New Territories, Hong Kong  
Country: China

Country of Incorporation: Hong Kong

3. Nature of Conveyance: Assignment

Execution Date: June 19, 2008

4. This document is being filed with a new application,  
the execution date of which is: June 19, 2008

5. Name and address of party to whom correspondence document should be mailed:

Guy D. Yale, Esq.  
Alix, Yale & Ristas, LLP  
750 Main Street, Suite 1400  
Hartford, CT 06103-2721

6. Total number of applications involved: 1

7. Total fee enclosed: \$40.00. If this amount is incorrect, please charge or credit the difference to Deposit Account No. 16-2563.

8. Total number of pages including cover sheet, attachments and documents: 3

To the best of my knowledge and belief, the foregoing information is true and correct.

**SIGNATURE OF APPLICANT, ATTORNEY OR AGENT**

Firm or Individual name

Guy D. Yale

Reg. No.

06/27/2008 MJAMA1 00000021 29308516

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40.00 DP

Signature

Date

June 20, 2008

Attorney's Docket No.

CHU/420DES/US

U.S. PTO  
  
29308516  
062008

EV610889707US

6.20.08

Attorney Docket: \_\_\_\_\_

**ASSIGNMENT**

WHEREAS, I, Kai-Shun Mak, residing at Block A1-A3, 7/F., Yip Fung Industrial Building, 28-36 Kwai Fung Crescent, Kwai Chung, New Territories, Hong Kong, China, have invented new and useful improvements in

Toy Drawings Board

for which I am making application for Letters Patent of the United States, which application was executed by me on the 19 day of June 2008; and

WHEREAS, Hop Lee Cheong Industrial Company Limited, a corporation of Hong Kong, having a place of business at Block A1-A3, 7/F., Yip Fung Industrial Building, 28-36 Kwai Fung Crescent, Kwai Chung, New Territories, Hong Kong, China, is desirous of acquiring the entire right, title and interest in and to said improvements and any Letters Patent which may be granted thereon;

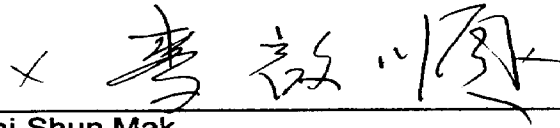
NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that for and in consideration of the sum of One (1) Dollar to me in hand paid and other good and valuable consideration, receipt of which is hereby acknowledged, I, the said Kai-Shun Mak, sell, assign and transfer to Hop Lee Cheong Industrial Company Limited, its successors and assigns (hereinafter called "Assignee"), the entire right, title and interest in and to said improvements and in and to any Letters Patent which may be obtained thereon in the United States and in all countries foreign thereto, together with said application and all divisional, continuing, substitute, renewal, reissue, and other applications for Letters Patent which have been or may be filed on said improvements in the United States or any other country, the same to be held and enjoyed by the Assignee for its and their sole use and behoof; and I do hereby further assign to the Assignee the right to file applications for patent in all countries on said improvements and all rights of priority resulting from any application for Letters Patent filed on said improvements.

I hereby authorize and request the Commissioner of Patents and Trademarks to issue all Letters Patent of the United States on said improvements to the Assignee.

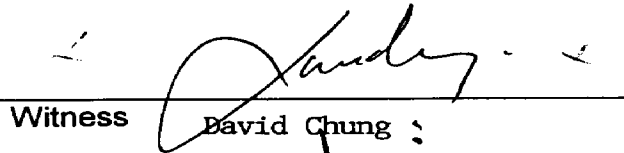
I further covenant and agree that when requested by the Assignee, and without further consideration, but at the cost and expense of the Assignee, I will, for any and all countries, execute and deliver all applications for patent on said improvements, execute all lawful oaths and other papers, supply to the Assignee all facts and evidence known to me relating to said improvements and the history and development thereof, testify in all interferences, suits, and other legal proceedings, and generally do everything rightful which the Assignee shall consider desirable for aiding in securing, maintaining, and enforcing proper patent protection for said improvements and for vesting the title to said improvements in the Assignee.

I further covenant that I have the lawful right to assign the interest in said improvements in the manner and form as herein expressed and that the interests herein conveyed are free from prior assignment, grant, mortgage, license, or other encumbrance whatsoever and that the execution of this Assignment is my own free act and deed.

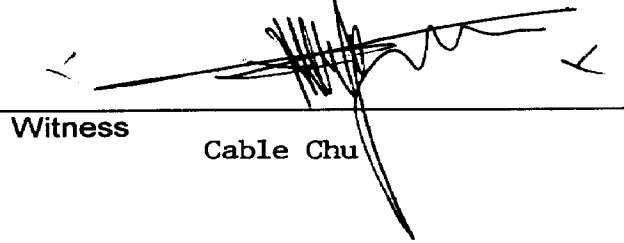
Date: 19 June 2008



Kai-Shun Mak



Witness David Chung :



Witness Cable Chu